



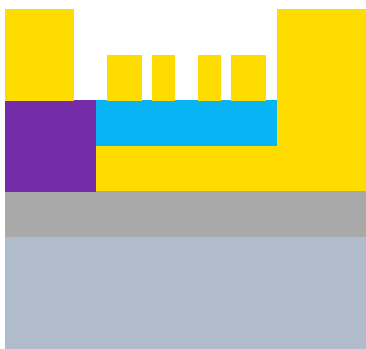
1. Electrode Exposure



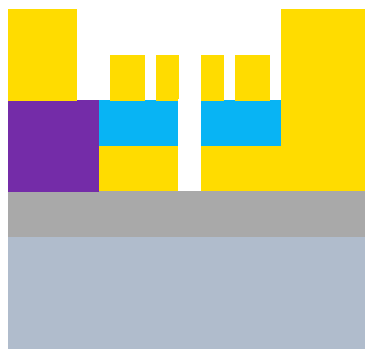
2. Active Area Etch



3. SiO₂ Backfill



4. 3x Metal Deposition



5. Release Window Etch



6. XeF₂ Release

